



IEEE MTT-S International Microwave Workshop Series on 5G Hardware and System Technologies

August 30th- 31st, 2018

Dublin, Ireland

CALL FOR PAPERS

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SCOPE

The next generation mobile network, the 5G, is expected to unlock many new services and provide a platform to enable growth in many industries. To bring 5G to reality, there are countless challenges lying ahead. Many of the most difficult scientific challenges are located at the “Physical Layer”, due to some fundamental limitations imposed by the nature of electromagnetic energy used. As a result, significant research is required to enable advanced microelectronic circuits and smart hardware implementation to achieve a working system. The IMWS-5G 2018 workshop provides a unique opportunity to bring together researchers and practitioners of different background to share the most recent advances in hardware and system technologies for 5G.

IMWS-5G 2018 will feature a two-day archival series of oral and poster presentations (in IEEE Xplore) with invited talks and tutorials. An industrial exhibit featuring a selection of state-of-the-art wireless and microwave products, measurement instruments and CAD software tools will also be held. The participation of young researchers and postgraduate students is strongly encouraged. Best Student Paper Awards will be made and a number of Young Researcher Travel Grants are available.

TOPICS

Technical contents include, but not limited to, the following areas:

- 5G RF/millimeter-wave transceiver architectures
- Highly integrated front-end modules and mixed-signal ICs
- Large-scale phased-array, beamformers, MIMO antennas
- High efficiency and broadband power amplifiers
- Signal generation, modulation and frequency conversion
- Reconfigurable circuit elements, filters, multiplexers
- IoT sensors, RFID circuits/chips for 5G applications
- RF/Microwave device, circuit and subsystem modelling
- OTA measurement, device/circuit characterization
- Energy harvesting, wireless power transfer circuits
- Nonlinear circuit/system analysis and simulation tools

IMPORTANT DATES

Abstract Submission Deadline:

April 16th, 2018

Notification of Acceptance:

June 30th, 2018

Final Manuscript Due:

July 20th, 2018

Conference Date:

August 30th-31st, 2018

SUBMISSIONS

Prospective authors are invited to submit a **three-page** extended abstract in PDF format before the Abstract Submission Deadline. All papers must be written in English, and submitted electronically from the conference website.

All submissions will be peer-reviewed. Authors of accepted contributions should provide a full-length (three-page) final version of their work before the Final Manuscript Submission Deadline. The final version of the paper will be published in the conference proceedings as well as submitted for inclusion in **IEEE Xplore Digital Library** provided it has been presented at the conference.

